

**Notic of Referenc s Cited**

Application/Control No.

09/961,036

Applicant(s)/Patent Under  
Reexamination  
DATTA ET AL.

Examiner

Erik Kielin

Art Unit

2813

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-4,290,079	09-1981	Carpenter et al.	257/780
	B	US-4,360,142	11-1982	Carpenter et al.	228/123.1
	C	US-5,376,584	12-1994	Agarwala, Birendra N.	438/614
	D	US-6,111,321	08-2000	Agarwala, Birendra Nath	257/772
	E	US-6,348,730 B1	02-2002	Yi et al.	257/737
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	JP 2001189334 A	07-2001	Japan	RI et al.	H01L 21/60
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	IBM Technical Disclosure Bulletin NN77081005, Vol 20, No. 3, August 1977, pp. 1005-1006.
	V	Microelectronics Packaging Handbook, Semiconductor Packaging, Part II, 2nd edition, Tummala, et al. eds., Kluwer Academic Publishers: Boston, 1997, pp. 132-139.
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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